

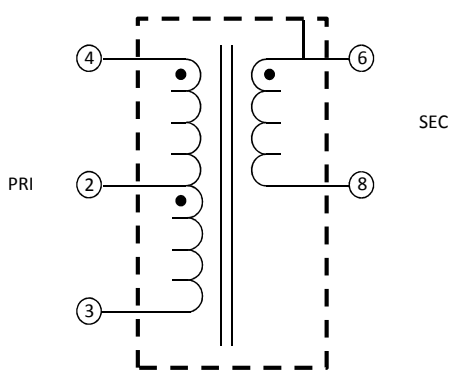
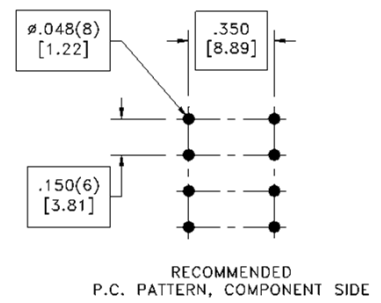
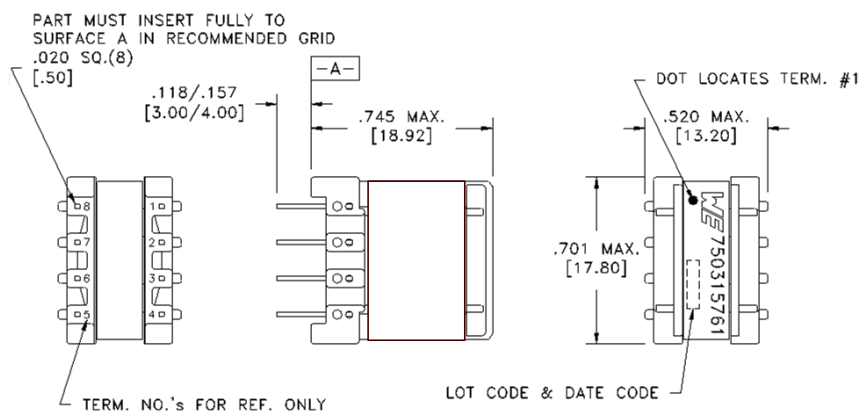
CUSTOMER TERMINAL	RoHS	LEAD(Pb)--FREE
Sn 96%, Ag 4%	Yes	Yes

more than you expect



ELECTRICAL SPECIFICATIONS @ 25° C unless otherwise noted:

PARAMETER	TEST CONDITIONS	VALUE
D.C. RESISTANCE	4-3 @20°C	1.16 ohms ±10%
D.C. RESISTANCE	6-8 @20°C	0.045 ohms ±20%
INDUCTANCE	4-3 10kHz, 100mV, Ls	880µH ±10%
SATURATION CURRENT	4-3 20% rolloff from initial	__ mA
LEAKAGE INDUCTANCE	4-3 tie(6+8), 100kHz, 100mV, Ls	3.5µH typ., __µH max.
DIELECTRIC	1-8 625VAC, 1 second	
URNS RATIO	(2-3):(4-2)	1:1, ±1%
URNS RATIO	(4-3):(6-8)	4.47:1, ±1%



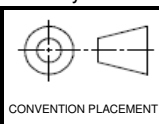
GENERAL SPECIFICATIONS:

OPERATING TEMPERATURE RANGE: -40°C to +125°C including temp rise.
 - Functional insulation only

Preliminary

Wire insulation & RoHS status not affected by wire color. Wire insulation color may vary depending on availability.

DFM	SP	Packaging Specifications
DATE	8/27/2015	Method: Tray
ENG	KLM	PKG-0168
REV.	00	
DATE	8/28/2015	www.we-online.com/midcom



Tolerances unless otherwise specified:
 Angles: ±1° Decimals: ±.005 [.13]
 Fractions: ±1/64 Footprint: ±.001 [.03]

This drawing is dual dimensioned. Dimensions in brackets are in millimeters.

DRAWING TITLE	PART NO.
TRANSFORMER	750315761
	SPECIFICATION SHEET 1 OF 1

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